

PATENT NUMBER

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| DIPE | PATENT DATE |
| AG 1 | |
| SCANNED AS 4 Q.A. | |

EXAMINER

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Conductive integrated circuit metal alloy interconnections, electroplating anodes; metal alloys for use as a conductive interconnection in an integrated circuit; and physical vapor deposition targets

PTO-2040
12/99

| ISSUING CLASSIFICATION | | | | | | | | | | | | |
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| ORIGINAL | | | | CROSS REFERENCE(S) | | | | | | | | |
| CLASS | | SUBCLASS | | CLASS | SUBCLASS (ONE SUBCLASS PER BLOCK) | | | | | | | |
| INTERNATIONAL CLASSIFICATION | | | | | | | | | | | | |
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| Total Claims | Print Claim for O.G. |
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(Legal Instruments Examiner)

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